



***The 2024 IEEE VLSI Symposium on Technology & Circuits
Announces Call for Papers on the Theme:
“Bridging the Digital & Physical Worlds with Efficiency & Intelligence”***

HONOLULU, HI (October 24, 2023) – For the last 44 years, the IEEE Symposium on VLSI Technology & Circuits has delivered a unique convergence of technology and circuits for the microelectronics industry. Merged into one Symposium since 2022 to maximize the synergy across both domains, the 2024 IEEE VLSI Symposium on Technology & Circuits has announced a call for papers around the theme: “Bridging the Digital & Physical Worlds with Efficiency & Intelligence.” The five-day event will be fully in-person with live sessions at the Hilton Hawaiian Village, Honolulu, HI, on June 16 – 20, 2024, as well as on-demand access to technical sessions starting the following week. The Symposium will feature the latest VLSI technology developments, innovative circuit design, and the applications they enable, such as artificial intelligence, machine learning, IoT, wearable/implantable biomedical applications, big data, cloud / edge computing, virtual reality (VR) / augmented reality (AR), robotics, and autonomous vehicles.

The Symposium submission site will open on December 5, 2023, and the deadline for paper submissions is February 5, 2024 at 23:59 PST. Complete details for paper submission can be found online at: <https://www.vlsisymposium.org/first-announcement-and-call-for-papers/>

The **IEEE VLSI Symposium on Technology & Circuits** seeks papers focusing on technical innovation and advances in the following areas:

- Advanced CMOS Platforms, Interconnect & Backside Power Delivery Network (BSPDN) Technologies
- Advanced Packaging, Chiplet & Heterogeneous Integration Technologies Including 2.5D & 3D
- Analog and Mixed-Signal Circuits
- Beyond CMOS Devices That Utilize New Physics Including Spin, Optical & Quantum Computing
- Biomedical Devices, Circuits & Systems
- Data Converters
- Device Physics, Characterization, Modeling & Reliability
- Devices & Accelerators For ML/DL & New Compute
- Digital Circuits, Hardware Security, Signal Integrity & I/Os
- DTCO & Design Enablement
- Frequency Generation & Clocking Circuits
- Memory Technologies, Devices, Circuits & Architectures
- Power Management Devices & Circuits
- Processes & Materials for CMOS Scaling & New Devices
- Processors & SoCs
- Sensors, Imagers, IoT, MEMS, Display Circuits
- Wireless and RF Devices, Circuits & Systems

The Symposium will continue its reputation as the microelectronics industry's premier international conference integrating technology, circuits, and systems with a range and scope unlike any other conference. In addition to the technical presentations, the Symposium program will feature a demonstration session for outstanding papers, evening panel discussions, joint focus sessions, Short Courses, and workshops on specific topics relevant to the Symposium theme.

Special events at the Symposium include career mentoring events for Women in Engineering and Young Professionals sponsored by the IEEE Electron Devices Society and the Solid State Circuits Society, and a traditional Hawaiian luau celebration.

Best Student Paper Awards for each track of the Symposium are chosen based on the quality of the papers and presentations. The recipients will receive a monetary award, travel cost support, and a certificate. For a paper to be reviewed for this award, the lead author and presenter of the paper must be enrolled as a full-time student at the time of submission, and must indicate on the web submission form that the paper is a student paper.

Further Information and Official Call for Papers

Visit: <http://www.vlsisymposium.org>.

Sponsoring Organizations

The IEEE VLSI Symposium on Technology & Circuits is sponsored by the the IEEE Electron Devices Society, in cooperation with the IEEE Solid State Circuits Society and Japan Society of Applied Physics, in cooperation with the Institute of Electronics, Information and Communication Engineers.

Media Contacts

(North America and EU)

BtB Integrated Marketing – Chris Burke, co-Media Relations Director

E-mail: chris.burke@btbmarketing.com

(Japan and Asia)

Secretariat for VLSI Symposia c/o JTB Communication Design, Inc.

Tokyo, Japan

E-mail: vlsisymp@jtbc.com